

Self-leveling, withstands high humidity environments

5108 is a one part, black, electrically isolating, precision mixed, degassed, and frozen epoxy compound specifically designed for potting and sealing electronic components. 5108 is a self leveling material that exhibits low shrinkage once cured and can withstand high temperatures and high humidity or wet environments. This material is also environmentally friendly and considered non-hazardous per D.O.T. regulations.

| | | | |
|------------------------------|---------------------------------|----------------|-----------------|
| UNCURED | | | |
| Pot Life @ 25°C | 2 hours | | |
| Viscosity @ 25°C | 5,000 cPs | | |
| Shelf Life @ -40°C | 6 months | | |
| CURE OPTIONS | 1 hour @ 92°C | 4 hours @ 65°C | 48 hours @ 25°C |
| CURED PROPERTIES | Based on cure of 4 hours @ 65°C | | |
| Color | Black | | |
| Shore D Hardness | 80 | | |
| Density (g/cc) | 1.07 | | |
| Glass Transition Temp (°C) | 45 | | |
| Shrinkage Linear (%) | 0.26 | | |
| ELECTRICAL PROPERTIES | Based on cure of 4 hours @ 65°C | | |
| Dielectric Constant | 3.2 @ 1 kHz | | |
| Dissipation Factor | 0.008 @ 1 kHz | | |
| Volume Resistivity (ohm-cm) | 7.0E 13 @ 500 VDC | | |
| THERMAL PROPERTIES | Based on cure of 4 hours @ 65°C | | |
| Glass Transition Temp (°C) | 45 | | |
| Degradation Temp. (°C) | 275 | | |
| OUTGASSING PROPERTIES | Based on cure of 4 hours @ 65°C | | |
| TML (%) | 0.75 | | |
| CVCM (%) | 0.01 | | |
| WVR (%) | 0.39 | | |
| ACOUSTIC PROPERTIES | | | |
| Velocity (m/s) | 2,345 | | |
| Impedance (MRayles) | 2.51 | | |
| Loss (dB/cm-MHz) | -4.83 | | |
| Density (g/cc) | 1.07 | | |

KEY FEATURES

Adheres to Dissimilar Materials

Self Leveling

Hydrolytic Stability

High Temperature Resistant

Low Shrinkage

Non-hazardous per D.O.T. Regulations

Talk to an engineer:

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Rev D

2/3/2017